

RESIN MOLDED PRODUCT MANUFACTURING APPARATUS, RESIN
MOLDING SYSTEM, AND RESIN MOLDED PRODUCT MANUFACTURING
METHOD

5 ABSTRACT OF THE DISCLOSURE

There is provided a resin molded product manufacturing apparatus, resin molding system, and resin molded product manufacturing method that can reduce variation in thickness of a resin molded product. The resin molded product manufacturing apparatus includes a first platen, a first mold chase holder provided on
10 the first platen, and a second platen disposed so as to face the first platen. The first mold chase holder includes a first heat insulating member on a side closer to the first platen, and a first mold chase holder heater on a side closer to the second platen. The first platen includes a first platen heater configured to heat the first platen.

15 FIG. 1